

## CLAIMS

The current claim set of the application is presented below. Indications as to the status of the claims ("original", "currently amended", "cancelled", "new", etc.) appear in parentheses after the claim number. Deletions are identified in bold with single brackets and strikethrough (e.g. [deletion]) and new text is identified with underlining (e.g. new language).

### Claims:

1. (Currently Amended) A method of protecting the interior of a mold, the method comprising:
  - providing a mold;
  - coating the interior of the mold with an etchant-resistant material;
  - applying a photosensitive mask over a portion of the etchant-resistant material while leaving other portions of the etchant-resistant material exposed;
  - selectively removing the exposed portions of the etchant-resistant material; and
  - etching those portions of the mold that are exposed.
2. (Original) The method of claim 1, wherein the mask is readily stretchable by at least 10 percent.
3. (Currently Amended) The method of claim 1, wherein the mask is wetted to increase its stretchability prior to applying it over the ~~acid resistant~~ etch-resistant material.
4. (Original) The method of claim 1, wherein the mask comprises an ethylenically unsaturated material.

**AMENDMENT AND RESPONSE**

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5. (Currently Amended) A method of protecting the interior of a mold, the method comprising:

providing a mold;

coating the interior of the mold with an acid-resistant material;

providing a photosensitive laminate containing a photosensitive material;

removing a portion of the photosensitive laminate;

subsequently applying the photosensitive laminate over the acid-resistant material coating the interior of the mold;

selectively removing a portion of the acid-resistant material corresponding to the removed portions of the photosensitive laminate using an abrasive.

etching those portions of the mold that are exposed.

6. (Original) The method of claim 5, wherein the photosensitive laminate is readily stretchable by at least 10 percent.

7. (Currently Amended) The method of claim 5, wherein [he] the photosensitive laminate is wetted to increase its stretchability prior to applying it over the acid-resistant material.

8. (Original) The method of claim 5, wherein the photosensitive material is developable with aqueous media.

9. (Original) The method of claim 5, wherein the photosensitive material comprises a photopolymer.

10. (Original) The method of claim 5, wherein the photosensitive material comprises a photoinitiator and a monomer, an oligomer, or a combination of monomer and oligomer.

11. (Currently Amended) The method of claim 5, wherein the photosensitive material comprises an [e] ethylenically unsaturated material.

12. (Original) The method of claim 5, wherein the photosensitive material comprises an acrylate material.

13. (Original) The method of claim 5, wherein the photosensitive material comprises a water-soluble, photosensitive vinyl polymer.

{13.} 14. (Currently Amended) The method of claim 13, wherein the water soluble, photosensitive vinyl polymer comprises a polyvinyl alcohol polymer.

{14.} 15. (Currently Amended) The method of claim 5, wherein the photosensitive layer comprises less than 75% by weight of a water soluble, photosensitive vinyl polymer having pendent hydroxyl groups and being capable of photo-generated insolubility and less than 75 weight percent of a polymeric film-forming binder.

~~[§5.]~~ 16. (Currently Amended) The method of claim 5, wherein the photopolymer has pendant, photo-crosslinkable, styryl groups.

~~[§6.]~~ 17. (Currently Amended) The method of claim 5, wherein the photosensitive material comprises less than 50 weight percent of a photopolymer, about 30 to 90 weight percent of a binder resin, and about 0 to 40 weight percent of a compatible plasticizers.

~~[§7.]~~ 18. (Currently Amended) The method of claim 13, wherein the photosensitive material comprises about 15 to 50 weight percent of a photopolymer having pendant, photo-crosslinkable, styryl groups, about 50 to 80 weight percent of a binder resin, and about 0 to 15 weight percent of a compatible plasticizer.

~~[§8.]~~ 19. (Currently Amended) The method of claim ~~[§7.]~~ 18, wherein the first layer photosensitive material further comprises a plasticizer.

~~[§3.]~~ 20. (Currently Amended) The method of claim 5, wherein the laminate further comprises a support layer.

~~[§20.]~~ 21. (Cancelled) The method of claim 5, wherein the photosensitive laminate film is flexible.